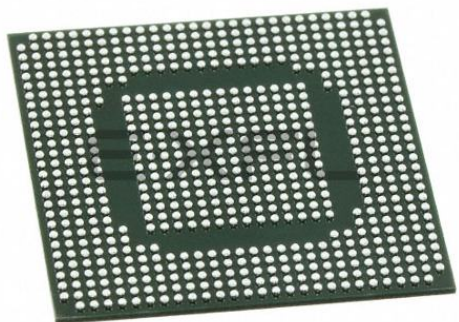


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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems



Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are Embedded - System On Chip (SoC)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details

Product Status	Active
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	600MHz
Primary Attributes	FPGA - 25K Logic Elements
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-FBGA
Supplier Device Package	672-UBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5cseba2u23c8n



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Cyclone V Device Overview

The Cyclone® V devices are designed to simultaneously accommodate the shrinking power consumption, cost, and time-to-market requirements; and the increasing bandwidth requirements for high-volume and cost-sensitive applications.

Enhanced with integrated transceivers and hard memory controllers, the Cyclone V devices are suitable for applications in the industrial, wireless and wireline, military, and automotive markets.

Related Information

[Cyclone V Device Handbook: Known Issues](#)

Lists the planned updates to the Cyclone V Device Handbook chapters.

Key Advantages of Cyclone V Devices

Table 1. Key Advantages of the Cyclone V Device Family

Advantage	Supporting Feature
Lower power consumption	<ul style="list-style-type: none"> Built on TSMC's 28 nm low-power (28LP) process technology and includes an abundance of hard intellectual property (IP) blocks Up to 40% lower power consumption than the previous generation device
Improved logic integration and differentiation capabilities	<ul style="list-style-type: none"> 8-input adaptive logic module (ALM) Up to 13.59 megabits (Mb) of embedded memory Variable-precision digital signal processing (DSP) blocks
Increased bandwidth capacity	<ul style="list-style-type: none"> 3.125 gigabits per second (Gbps) and 6.144 Gbps transceivers Hard memory controllers
Hard processor system (HPS) with integrated Arm* Cortex*-A9 MPCore* processor	<ul style="list-style-type: none"> Tight integration of a dual-core Arm Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Cyclone V system-on-a-chip (SoC) Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric
Lowest system cost	<ul style="list-style-type: none"> Requires only two core voltages to operate Available in low-cost wirebond packaging Includes innovative features such as Configuration via Protocol (CvP) and partial reconfiguration

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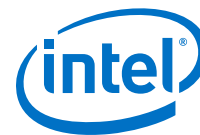
Summary of Cyclone V Features

Table 2. Summary of Features for Cyclone V Devices

Feature	Description	
Technology	<ul style="list-style-type: none"> TSMC's 28-nm low-power (28LP) process technology 1.1 V core voltage 	
Packaging	<ul style="list-style-type: none"> Wirebond low-halogen packages Multiple device densities with compatible package footprints for seamless migration between different device densities RoHS-compliant and leaded⁽¹⁾ options 	
High-performance FPGA fabric	Enhanced 8-input ALM with four registers	
Internal memory blocks	<ul style="list-style-type: none"> M10K—10-kilobits (Kb) memory blocks with soft error correction code (ECC) Memory logic array block (MLAB)—640-bit distributed LUTRAM where you can use up to 25% of the ALMs as MLAB memory 	
Embedded Hard IP blocks	Variable-precision DSP	<ul style="list-style-type: none"> Native support for up to three signal processing precision levels (three 9 x 9, two 18 x 18, or one 27 x 27 multiplier) in the same variable-precision DSP block 64-bit accumulator and cascade Embedded internal coefficient memory Padder/subtractor for improved efficiency
	Memory controller	DDR3, DDR2, and LPDDR2 with 16 and 32 bit ECC support
	Embedded transceiver I/O	PCI Express* (PCIe*) Gen2 and Gen1 (x1, x2, or x4) hard IP with multifunction support, endpoint, and root port
Clock networks	<ul style="list-style-type: none"> Up to 550 MHz global clock network Global, quadrant, and peripheral clock networks Clock networks that are not used can be powered down to reduce dynamic power 	
Phase-locked loops (PLLs)	<ul style="list-style-type: none"> Precision clock synthesis, clock delay compensation, and zero delay buffering (ZDB) Integer mode and fractional mode 	
FPGA General-purpose I/Os (GPIOs)	<ul style="list-style-type: none"> 875 megabits per second (Mbps) LVDS receiver and 840 Mbps LVDS transmitter 400 MHz/800 Mbps external memory interface On-chip termination (OCT) 3.3 V support with up to 16 mA drive strength 	
Low-power high-speed serial interface	<ul style="list-style-type: none"> 614 Mbps to 6.144 Gbps integrated transceiver speed Transmit pre-emphasis and receiver equalization Dynamic partial reconfiguration of individual channels 	
HPS (Cyclone V SE, SX, and ST devices only)	<ul style="list-style-type: none"> Single or dual-core Arm Cortex-A9 MPCore processor-up to 925 MHz maximum frequency with support for symmetric and asymmetric multiprocessing Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-Go (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, controller area network (CAN), serial peripheral interface (SPI), I²C interface, and up to 85 HPS GPIO interfaces System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers On-chip RAM and boot ROM 	

continued...

⁽¹⁾ Contact Intel for availability.



Feature	Description
	<ul style="list-style-type: none"> HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller Arm CoreSight™ JTAG debug access port, trace port, and on-chip trace storage
Configuration	<ul style="list-style-type: none"> Tamper protection—comprehensive design protection to protect your valuable IP investments Enhanced advanced encryption standard (AES) design security features CvP Dynamic reconfiguration of the FPGA Active serial (AS) x1 and x4, passive serial (PS), JTAG, and fast passive parallel (FPP) x8 and x16 configuration options Internal scrubbing ⁽²⁾ Partial reconfiguration ⁽³⁾

Cyclone V Device Variants and Packages

Table 3. Device Variants for the Cyclone V Device Family

Variant	Description
Cyclone V E	Optimized for the lowest system cost and power requirement for a wide spectrum of general logic and DSP applications
Cyclone V GX	Optimized for the lowest cost and power requirement for 614 Mbps to 3.125 Gbps transceiver applications
Cyclone V GT	The FPGA industry's lowest cost and lowest power requirement for 6.144 Gbps transceiver applications
Cyclone V SE	SoC with integrated Arm-based HPS
Cyclone V SX	SoC with integrated Arm-based HPS and 3.125 Gbps transceivers
Cyclone V ST	SoC with integrated Arm-based HPS and 6.144 Gbps transceivers

Cyclone V E

This section provides the available options, maximum resource counts, and package plan for the Cyclone V E devices.

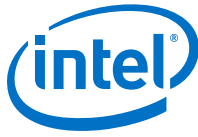
The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Product Selector Guide.

Related Information

Product Selector Guide

Provides the latest information about Intel products.

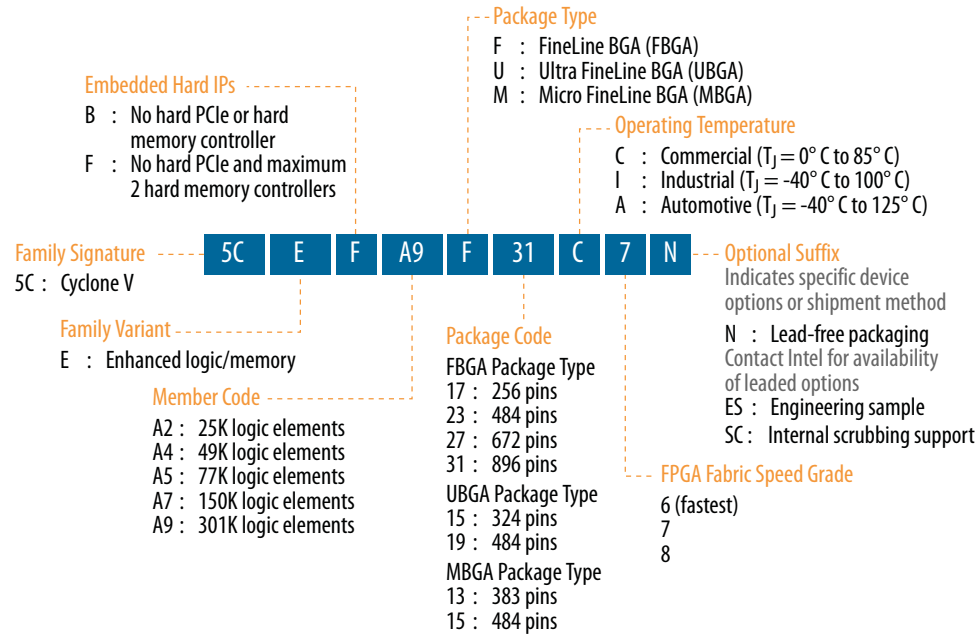
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- ⁽²⁾ The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.
- ⁽³⁾ The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel® sales representatives.



Available Options

Figure 1. Sample Ordering Code and Available Options for Cyclone V E Devices

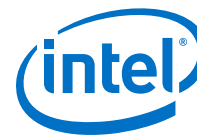
The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Maximum Resources

Table 4. Maximum Resource Counts for Cyclone V E Devices

Resource		Member Code				
		A2	A4	A5	A7	A9
Logic Elements (LE) (K)		25	49	77	150	301
ALM		9,430	18,480	29,080	56,480	113,560
Register		37,736	73,920	116,320	225,920	454,240
Memory (Kb)	M10K	1,760	3,080	4,460	6,860	12,200
	MLAB	196	303	424	836	1,717
Variable-precision DSP Block		25	66	150	156	342
18 x 18 Multiplier		50	132	300	312	684
PLL		4	4	6	7	8
GPIO		224	224	240	480	480
LVDS	Transmitter	56	56	60	120	120
	Receiver	56	56	60	120	120
Hard Memory Controller		1	1	2	2	2



Related Information

[True LVDS Buffers in Devices, I/O Features in Cyclone V Devices](#)

Provides the number of LVDS channels in each device package.

Package Plan

Table 5. Package Plan for Cyclone V E Devices

Member Code	M383 (13 mm)	M484 (15 mm)	U324 (15 mm)	F256 (17 mm)	U484 (19 mm)	F484 (23 mm)	F672 (27 mm)	F896 (31 mm)
	GPIO	GPIO	GPIO	GPIO	GPIO	GPIO	GPIO	GPIO
A2	223	—	176	128	224	224	—	—
A4	223	—	176	128	224	224	—	—
A5	175	—	—	—	224	240	—	—
A7	—	240	—	—	240	240	336	480
A9	—	—	—	—	240	224	336	480

Cyclone V GX

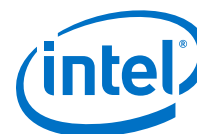
This section provides the available options, maximum resource counts, and package plan for the Cyclone V GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

[Product Selector Guide](#)

Provides the latest information about Intel products.



Resource		Member Code				
		C3	C4	C5	C7	C9
LVDS	Transmitter	52	84	84	120	140
	Receiver	52	84	84	120	140
PCIe Hard IP Block		1	2	2	2	2
Hard Memory Controller		1	2	2	2	2

Related Information

[True LVDS Buffers in Devices, I/O Features in Cyclone V Devices](#)

Provides the number of LVDS channels in each device package.

Package Plan

Table 7. Package Plan for Cyclone V GX Devices

Member Code	M301 (11 mm)		M383 (13 mm)		M484 (15 mm)		U324 (15 mm)		U484 (19 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
C3	—	—	—	—	—	—	144	3	208	3
C4	129	4	175	6	—	—	—	—	224	6
C5	129	4	175	6	—	—	—	—	224	6
C7	—	—	—	—	240	3	—	—	240	6
C9	—	—	—	—	—	—	—	—	240	5

Member Code	F484 (23 mm)		F672 (27 mm)		F896 (31 mm)		F1152 (35 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
C3	208	3	—	—	—	—	—	—
C4	240	6	336	6	—	—	—	—
C5	240	6	336	6	—	—	—	—
C7	240	6	336	9	480	9	—	—
C9	224	6	336	9	480	12	560	12

Cyclone V GT

This section provides the available options, maximum resource counts, and package plan for the Cyclone V GT devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

[Product Selector Guide](#)

Provides the latest information about Intel products.



Resource		Member Code		
		D5	D7	D9
	Receiver	84	120	140
PCIe Hard IP Block		2	2	2
Hard Memory Controller		2	2	2

Related Information

[True LVDS Buffers in Devices, I/O Features in Cyclone V Devices](#)

Provides the number of LVDS channels in each device package.

Package Plan

Table 9. Package Plan for Cyclone V GT Devices

Transceiver counts shown are for transceiver ≤ 5 Gbps. 6 Gbps transceiver channel count support depends on the package and channel usage. For more information about the 6 Gbps transceiver channel count, refer to the *Cyclone V Device Handbook Volume 2: Transceivers*.

Member Code	M301 (11 mm)		M383 (13 mm)		M484 (15 mm)		U484 (19 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
D5	129	4	175	6	—	—	224	6
D7	—	—	—	—	240	3	240	6
D9	—	—	—	—	—	—	240	5

Member Code	F484 (23 mm)		F672 (27 mm)		F896 (31 mm)		F1152 (35 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
D5	240	6	336	6	—	—	—	—
D7	240	6	336	9 ⁽⁶⁾	480	9 ⁽⁶⁾	—	—
D9	224	6	336	9 ⁽⁶⁾	480	12 ⁽⁷⁾	560	12 ⁽⁷⁾

Related Information

[6.144-Gbps Support Capability in Cyclone V GT Devices, Cyclone V Device Handbook Volume 2: Transceivers](#)

Provides more information about 6 Gbps transceiver channel count.

-
- ⁽⁶⁾ If you require CPRI (at 6.144 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to three full-duplex transceiver channels for CPRI, and up to six full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.
- ⁽⁷⁾ If you require CPRI (at 6.144 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to three full-duplex transceiver channels for CPRI, and up to eight full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.



Maximum Resources

Table 10. Maximum Resource Counts for Cyclone V SE Devices

Resource		Member Code			
		A2	A4	A5	A6
Logic Elements (LE) (K)		25	40	85	110
ALM		9,430	15,880	32,070	41,910
Register		37,736	60,376	128,300	166,036
Memory (Kb)	M10K	1,400	2,700	3,970	5,570
	MLAB	138	231	480	621
Variable-precision DSP Block		36	84	87	112
18 x 18 Multiplier		72	168	174	224
FPGA PLL		5	5	6	6
HPS PLL		3	3	3	3
FPGA GPIO		145	145	288	288
HPS I/O		181	181	181	181
LVDS	Transmitter	32	32	72	72
	Receiver	37	37	72	72
FPGA Hard Memory Controller		1	1	1	1
HPS Hard Memory Controller		1	1	1	1
Arm Cortex-A9 MPCore Processor		Single- or dual-core	Single- or dual-core	Single- or dual-core	Single- or dual-core

Related Information

[True LVDS Buffers in Devices, I/O Features in Cyclone V Devices](#)

Provides the number of LVDS channels in each device package.

Package Plan

Table 11. Package Plan for Cyclone V SE Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U484 (19 mm)		U672 (23 mm)		F896 (31 mm)	
	FPGA GPIO	HPS I/O	FPGA GPIO	HPS I/O	FPGA GPIO	HPS I/O
A2	66	151	145	181	—	—
A4	66	151	145	181	—	—
A5	66	151	145	181	288	181
A6	66	151	145	181	288	181



Resource		Member Code			
		C2	C4	C5	C6
HPS PLL		3	3	3	3
3 Gbps Transceiver		6	6	9	9
FPGA GPIO ⁽⁸⁾		145	145	288	288
HPS I/O		181	181	181	181
LVDS	Transmitter	32	32	72	72
	Receiver	37	37	72	72
PCIe Hard IP Block		2	2	2 ⁽⁹⁾	2 ⁽⁹⁾
FPGA Hard Memory Controller		1	1	1	1
HPS Hard Memory Controller		1	1	1	1
Arm Cortex-A9 MPCore Processor		Dual-core	Dual-core	Dual-core	Dual-core

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

Package Plan

Table 13. Package Plan for Cyclone V SX Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U672 (23 mm)			F896 (31 mm)		
	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR
C2	145	181	6	—	—	—
C4	145	181	6	—	—	—
C5	145	181	6	288	181	9
C6	145	181	6	288	181	9

Cyclone V ST

This section provides the available options, maximum resource counts, and package plan for the Cyclone V ST devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

⁽⁸⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁹⁾ 1 PCIe Hard IP Block in U672 package.



Resource		Member Code	
		D5	D6
	Receiver	72	72
PCIe Hard IP Block		2	2
FPGA Hard Memory Controller		1	1
HPS Hard Memory Controller		1	1
Arm Cortex-A9 MPCore Processor		Dual-core	Dual-core

Related Information

[True LVDS Buffers in Devices, I/O Features in Cyclone V Devices](#)

Provides the number of LVDS channels in each device package.

Package Plan

Table 15. Package Plan for Cyclone V ST Devices

- The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.
- Transceiver counts shown are for transceiver ≤ 5 Gbps. 6 Gbps transceiver channel count support depends on the package and channel usage. For more information about the 6 Gbps transceiver channel count, refer to the *Cyclone V Device Handbook Volume 2: Transceivers*.

Member Code	F896 (31 mm)		
	FPGA GPIO	HPS I/O	XCVR
D5	288	181	9 ⁽¹¹⁾
D6	288	181	9 ⁽¹¹⁾

Related Information

[6.144-Gbps Support Capability in Cyclone V GT Devices, Cyclone V Device Handbook Volume 2: Transceivers](#)

Provides more information about 6 Gbps transceiver channel count.

⁽¹¹⁾ If you require CPRI (at 4.9152 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to seven full-duplex transceiver channels for CPRI, and up to six full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.

I/O Vertical Migration for Cyclone V Devices

Figure 7. Vertical Migration Capability Across Cyclone V Device Packages and Densities

The arrows indicate the vertical migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.

Variant	Member Code	Package										
		M301	M383	M484	F256	U324	U484	F484	U672	F672	F896	F1152
Cyclone V E	A2		↕	↕		↕	↕	↕				
	A4		↕		↕	↕	↕	↕				
	A5		↕									
	A7									↕	↕	
	A9						↕	↕		↕	↕	
Cyclone V GX	C3						↕	↕		↕	↕	
	C4	↕	↕							↕		
	C5	↕	↕									
	C7										↕	
	C9						↕	↕		↕	↕	
Cyclone V GT	D5						↕	↕		↕		
	D7									↕	↕	
	D9						↕	↕		↕	↕	
Cyclone V SE	A2						↕		↕	↕		
	A4								↕	↕		
	A5										↕	
	A6						↕		↕	↕	↕	
Cyclone V SX	C2								↕	↕		
	C4								↕	↕		
	C5										↕	
	C6								↕	↕	↕	
Cyclone V ST	D5										↕	
	D6										↕	

You can achieve the vertical migration shaded in red if you use only up to 175 GPIOs for the M383 package, and 138 GPIOs for the U672 package. These migration paths are not shown in the Intel Quartus Prime software Pin Migration View.

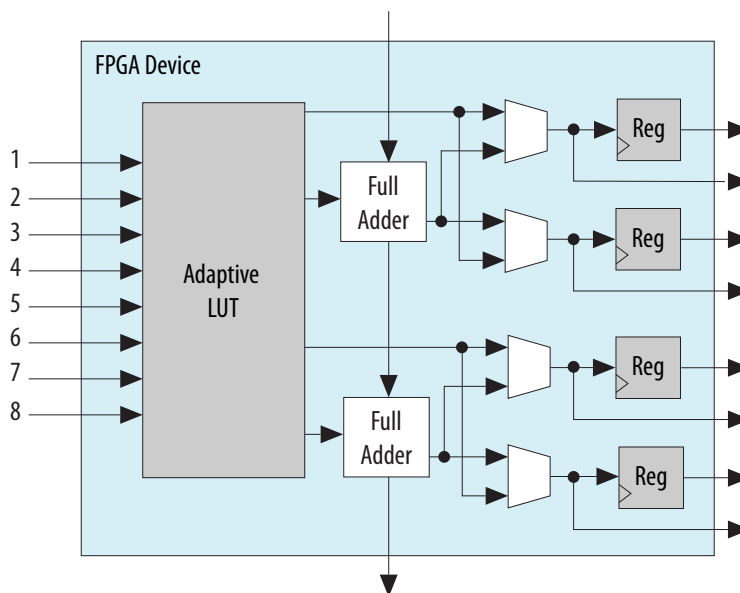
Note: To verify the pin migration compatibility, use the Pin Migration View window in the Intel Quartus Prime software Pin Planner.

Adaptive Logic Module

Cyclone V devices use a 28 nm ALM as the basic building block of the logic fabric.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than previous generations.

Figure 8. ALM for Cyclone V Devices



You can configure up to 25% of the ALMs in the Cyclone V devices as distributed memory using MLABs.

Related Information

[Embedded Memory Capacity in Cyclone V Devices](#) on page 21
Lists the embedded memory capacity for each device.

Variable-Precision DSP Block

Cyclone V devices feature a variable-precision DSP block that supports these features:

- Configurable to support signal processing precisions ranging from 9 x 9, 18 x 18 and 27 x 27 bits natively
- A 64-bit accumulator
- A hard preadder that is available in both 18- and 27-bit modes
- Cascaded output adders for efficient systolic finite impulse response (FIR) filters
- Internal coefficient register banks, 8 deep, for each multiplier in 18- or 27-bit mode
- Fully independent multiplier operation
- A second accumulator feedback register to accommodate complex multiply-accumulate functions
- Fully independent Efficient support for single-precision floating point arithmetic
- The inferability of all modes by the Intel Quartus Prime design software

Table 16. Variable-Precision DSP Block Configurations for Cyclone V Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resource
Low precision fixed point for video applications	Three 9 x 9	1
Medium precision fixed point in FIR filters	Two 18 x 18	1
FIR filters and general DSP usage	Two 18 x 18 with accumulate	1
High precision fixed- or floating-point implementations	One 27 x 27 with accumulate	1

You can configure each DSP block during compilation as independent three 9 x 9, two 18 x 18, or one 27 x 27 multipliers. With a dedicated 64 bit cascade bus, you can cascade multiple variable-precision DSP blocks to implement even higher precision DSP functions efficiently.

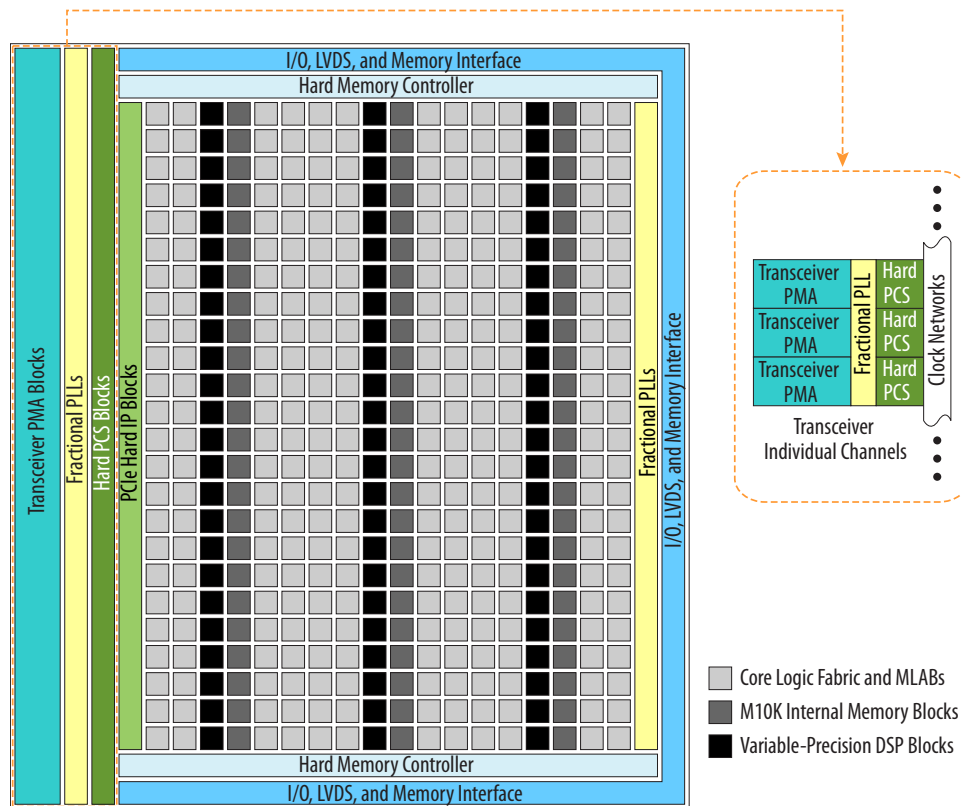
Table 17. Number of Multipliers in Cyclone V Devices

The table lists the variable-precision DSP resources by bit precision for each Cyclone V device.

Variant	Member Code	Variable-precision DSP Block	Independent Input and Output Multiplications Operator			18 x 18 Multiplier Adder Mode	18 x 18 Multiplier Adder Summed with 36 bit Input
			9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier		
Cyclone V E	A2	25	75	50	25	25	25
	A4	66	198	132	66	66	66
	A5	150	450	300	150	150	150
	A7	156	468	312	156	156	156
	A9	342	1,026	684	342	342	342
Cyclone V GX	C3	57	171	114	57	57	57
	C4	70	210	140	70	70	70
	C5	150	450	300	150	150	150
	C7	156	468	312	156	156	156
	C9	342	1,026	684	342	342	342
Cyclone V GT	D5	150	450	300	150	150	150
	D7	156	468	312	156	156	156
	D9	342	1,026	684	342	342	342
Cyclone V SE	A2	36	108	72	36	36	36
	A4	84	252	168	84	84	84
	A5	87	261	174	87	87	87
	A6	112	336	224	112	112	112
Cyclone V SX	C2	36	108	72	36	36	36
	C4	84	252	168	84	84	84
	C5	87	261	174	87	87	87
continued...							

Figure 10. Device Chip Overview for Cyclone V GX and GT Devices

The figure shows a Cyclone V FPGA with transceivers. Different Cyclone V devices may have a different floorplans than the one shown here.



PMA Features

To prevent core and I/O noise from coupling into the transceivers, the PMA block is isolated from the rest of the chip—ensuring optimal signal integrity. For the transceivers, you can use the channel PLL of an unused receiver PMA as an additional transmit PLL.

Table 22. PMA Features of the Transceivers in Cyclone V Devices

Features	Capability
Backplane support	Driving capability up to 6.144 Gbps
PLL-based clock recovery	Superior jitter tolerance
Programmable deserialization and word alignment	Flexible deserialization width and configurable word alignment pattern
Equalization and pre-emphasis	<ul style="list-style-type: none"> Up to 14.37 dB of pre-emphasis and up to 4.7 dB of equalization No decision feedback equalizer (DFE)
Ring oscillator transmit PLLs	614 Mbps to 6.144 Gbps
Input reference clock range	20 MHz to 400 MHz
Transceiver dynamic reconfiguration	Allows the reconfiguration of a single channel without affecting the operation of other channels



PCS Features

The Cyclone V core logic connects to the PCS through an 8, 10, 16, 20, 32, or 40 bit interface, depending on the transceiver data rate and protocol. Cyclone V devices contain PCS hard IP to support PCIe Gen1 and Gen2, Gbps Ethernet (GbE), Serial RapidIO® (SRIO), and Common Public Radio Interface (CPRI).

Most of the standard and proprietary protocols from 614 Mbps to 6.144 Gbps are supported.

Table 23. Transceiver PCS Features for Cyclone V Devices

PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
3-Gbps and 6-Gbps Basic	0.614 to 6.144	<ul style="list-style-type: none"> Phase compensation FIFO Byte serializer 8B/10B encoder Transmitter bit-slip 	<ul style="list-style-type: none"> Word aligner Deskew FIFO Rate-match FIFO 8B/10B decoder Byte deserializer Byte ordering Receiver phase compensation FIFO
PCIe Gen1 (x1, x2, x4)	2.5 and 5.0	<ul style="list-style-type: none"> Dedicated PCIe PHY IP core PIPE 2.0 interface to the core logic 	<ul style="list-style-type: none"> Dedicated PCIe PHY IP core PIPE 2.0 interface to the core logic
PCIe Gen2 (x1, x2, x4) ⁽¹²⁾			
GbE	1.25	<ul style="list-style-type: none"> Custom PHY IP core with preset feature GbE transmitter synchronization state machine 	<ul style="list-style-type: none"> Custom PHY IP core with preset feature GbE receiver synchronization state machine
XAUI ⁽¹³⁾	3.125	<ul style="list-style-type: none"> Dedicated XAUI PHY IP core XAUI synchronization state machine for bonding four channels 	<ul style="list-style-type: none"> Dedicated XAUI PHY IP core XAUI synchronization state machine for realigning four channels
HiGig	3.75		
SRIO 1.3 and 2.1	1.25 to 3.125	<ul style="list-style-type: none"> Custom PHY IP core with preset feature SRIO version 2.1-compliant x2 and x4 channel bonding 	<ul style="list-style-type: none"> Custom PHY IP core with preset feature SRIO version 2.1-compliant x2 and x4 deskew state machine
SDI, SD/HD, and 3G-SDI	0.27 ⁽¹⁴⁾ , 1.485, and 2.97	Custom PHY IP core with preset feature	Custom PHY IP core with preset feature
JESD204A	0.3125 ⁽¹⁵⁾ to 3.125		

continued...

⁽¹²⁾ PCIe Gen2 is supported for Cyclone V GT and ST devices. The PCIe Gen2 x4 support is PCIe-compatible.

⁽¹³⁾ XAUI is supported through the soft PCS.

⁽¹⁴⁾ The 0.27-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

⁽¹⁵⁾ The 0.3125-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.



PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
Serial ATA Gen1 and Gen2	1.5 and 3.0	<ul style="list-style-type: none">Custom PHY IP core with preset featureElectrical idle	<ul style="list-style-type: none">Custom PHY IP core with preset featureSignal detectWider spread of asynchronous SSC
CPRI 4.1 ⁽¹⁶⁾	0.6144 to 6.144	<ul style="list-style-type: none">Dedicated deterministic latency PHY IP coreTransmitter (TX) manual bit-slip mode	<ul style="list-style-type: none">Dedicated deterministic latency PHY IP coreReceiver (RX) deterministic latency state machine
OBSAI RP3	0.768 to 3.072		
V-by-One HS	Up to 3.75	Custom PHY IP core	<ul style="list-style-type: none">Custom PHY IP coreWider spread of asynchronous SSC
DisplayPort 1.2 ⁽¹⁷⁾	1.62 and 2.7		

SoC with HPS

Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

The HPS consists of a dual-core Arm Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

⁽¹⁶⁾ High-voltage output mode (1000-BASE-CX) is not supported.

⁽¹⁷⁾ Pending characterization.

Apart from lowering cost and power consumption, partial reconfiguration increases the effective logic density of the device because placing device functions that do not operate simultaneously is not necessary. Instead, you can store these functions in external memory and load them whenever the functions are required. This capability reduces the size of the device because it allows multiple applications on a single device—saving the board space and reducing the power consumption.

Intel simplifies the time-intensive task of partial reconfiguration by building this capability on top of the proven incremental compile and design flow in the Intel Quartus Prime design software. With the Intel solution, you do not need to know all the intricate device architecture details to perform a partial reconfiguration.

Partial reconfiguration is supported through the FPP x16 configuration interface. You can seamlessly use partial reconfiguration in tandem with dynamic reconfiguration to enable simultaneous partial reconfiguration of both the device core and transceivers.

Enhanced Configuration and Configuration via Protocol

Cyclone V devices support 1.8 V, 2.5 V, 3.0 V, and 3.3 V programming voltages and several configuration schemes.

Table 24. Configuration Schemes and Features Supported by Cyclone V Devices

Mode	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps)	Decompression	Design Security	Partial Reconfiguration ⁽¹⁸⁾	Remote System Update
AS through the EPCS and EPCQ serial configuration device	1 bit, 4 bits	100	—	Yes	Yes	—	Yes
PS through CPLD or external microcontroller	1 bit	125	125	Yes	Yes	—	—
FPP	8 bits	125	—	Yes	Yes	—	Parallel flash loader
	16 bits	125	—	Yes	Yes	Yes	
CvP (PCIe)	x1, x2, and x4 lanes	—	—	Yes	Yes	Yes	—
JTAG	1 bit	33	33	—	—	—	—

Instead of using an external flash or ROM, you can configure the Cyclone V devices through PCIe using CvP. The CvP mode offers the fastest configuration rate and flexibility with the easy-to-use PCIe hard IP block interface. The Cyclone V CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

Related Information

[Configuration via Protocol \(CvP\) Implementation in Intel FPGAs User Guide](#)

Provides more information about CvP.

⁽¹⁸⁾ The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Date	Version	Changes
July 2014	2014.07.07	Updated the I/O vertical migration figure to clarify the migration capability of Cyclone V SE and SX devices.
December 2013	2013.12.26	<ul style="list-style-type: none"> Corrected single or dual-core ARM Cortex-A9 MPCore processor-up to 925 MHz from 800 MHz. Removed "Preliminary" texts from Ordering Code figures, Maximum Resources, Package Plan and I/O Vertical Migration tables. Removed the note "The number of GPIOs does not include transceiver I/Os. In the Quartus II software, the number of user I/Os includes transceiver I/Os." for GPIOs in the Maximum Resource Counts table for Cyclone V E and SE. Added link to Altera Product Selector for each device variant. Updated Embedded Hard IPs for Cyclone V GT devices to indicate Maximum 2 hard PCIe and 2 hard memory controllers. Added leaded package options. Removed the note "The number of PLLs includes general-purpose fractional PLLs and transceiver fractional PLLs." for all PLLs in the Maximum Resource Counts table. Corrected max LVDS counts for transmitter and receiver for Cyclone V E A5 device from 84 to 60. Corrected max LVDS counts for transmitter and receiver for Cyclone V E A9 device from 140 to 120. Corrected variable-precision DSP block, 27 x 27 multiplier, 18 x 18 multiplier adder mode and 18 x 18 multiplier adder summed with 36 bit input for Cyclone V SE devices from 58 to 84. Corrected 18 x 18 multiplier for Cyclone V SE devices from 116 to 168. Corrected 9 x 9 multiplier for Cyclone V SE devices from 174 to 252. Corrected LVDS transmitter for Cyclone V SE A2 and A4 as well as SX C2 and C4 devices from 31 to 32. Corrected LVDS receiver for Cyclone V SE A2 and A4 as well as SX C2 and C4 devices from 35 to 37. Corrected transceiver speed grade for Cyclone V ST devices ordering code from 4 to 5. Updated the DDR3 SDRAM for the maximum frequency's soft controller and the minimum frequency from 300 to 303 for voltage 1.35V. Added links to Altera's External Memory Spec Estimator tool to the topics listing the external memory interface performance. Corrected XAUI is supported through the soft PCS in the PCS features for Cyclone V. Added decompression support for the CvP configuration mode.
May 2013	2013.05.06	<ul style="list-style-type: none"> Added link to the known document issues in the Knowledge Base. Moved all links to the Related Information section of respective topics for easy reference. Corrected the title to the PCIe hard IP topic. Cyclone V devices support only PCIe Gen1 and Gen2. Updated Supporting Feature in Table 1 of Increased bandwidth capacity to '6.144 Gbps'. Updated Description in Table 2 of Low-power high-speed serial interface to '6.144 Gbps'. Updated Description in Table 3 of Cyclone V GT to '6.144 Gbps'. Updated the M386 package to M383 for Figure 1, Figure 2 and Figure 3. Updated Figure 2 and Figure 3 for Transceiver Count by adding 'F : 4'. Updated LVDS in the Maximum Resource Counts tables to include Transmitter and Receiver values. Updated the package plan with M383 for the Cyclone V E device. Removed the M301 and M383 packages from the Cyclone V GX C4 device. Updated the GPIO count to '129' for the M301 package of the Cyclone V GX C5 device. Updated 5 Gbps to '6.144 Gbps' for Cyclone V GT device.

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Date	Version	Changes
		<ul style="list-style-type: none">Updated Figure 1, Figure 2, Figure 3, Figure 4, Figure 5, Figure 6, and Figure 10.Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections.Text edits throughout the document.
February 2012	1.2	<ul style="list-style-type: none">Updated Table 1-2, Table 1-3, and Table 1-6.Updated "Cyclone V Family Plan" on page 1-4 and "Clock Networks and PLL Clock Sources" on page 1-15.Updated Figure 1-1 and Figure 1-6.
November 2011	1.1	<ul style="list-style-type: none">Updated Table 1-1, Table 1-2, Table 1-3, Table 1-4, Table 1-5, and Table 1-6.Updated Figure 1-4, Figure 1-5, Figure 1-6, Figure 1-7, and Figure 1-8.Updated "System Peripherals" on page 1-18, "HPS-FPGA AXI Bridges" on page 1-19, "HPS SDRAM Controller Subsystem" on page 1-19, "FPGA Configuration and Processor Booting" on page 1-19, and "Hardware and Software Development" on page 1-20.Minor text edits.
October 2011	1.0	Initial release.